

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.: 10/648,407 Confirmation No.: 4026

Applicant(s): Adams et al.

Filed: 8/25/2003 Art Unit: 2833

Examiner:

Title: Interconnect For Electrically Connecting a Multichip

Module To A Circuit Substrate And Processes For Making

And Using Same

Attorney Docket No.: 003A.0035.U2(US)

Customer No.: 29,683

Commissioner For Patents P.O. Box 1450 Alexandria, VA 22313-1450

## Preliminary Amendment

## Sir:

Please amend the Application as indicated on the following pages.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begin on page 3 of this paper.

Remarks begin on page 8 of this paper.